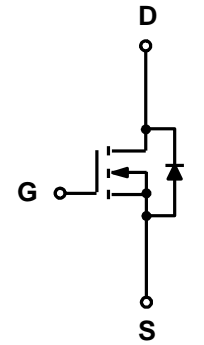


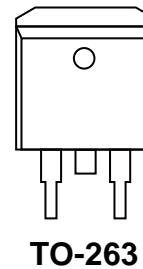
**Features**

- 150V,140A  
 $R_{DS(on)} < 7.5m\Omega @ V_{GS}=10V$  TYP:6.6m $\Omega$
- Extremely low losses due to very low FOM  $R_{dson} * Q_g$ .
- High-speed switching.
- Qualified for industrial grade applications according to JEDEC.
- 100% UIS Tested.



**Applications**

- Synchronous Rectification in SMPS
- Hard Switching and High Speed Circuit
- Power Tools
- UPS
- Motor Control



**Package Marking and Ordering Information**

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity (PCS)
G075N15D	APG075N15D	TO-263	-	-	800

**ABSOLUTE MAXIMUM RATINGS (T<sub>a</sub>=25°C unless otherwise noted)**

Parameter	Symbol	Value	Unit
Drain-Source Voltage <sup>(a)</sup>	V <sub>DS</sub>	150	V
Gate-Source Voltage	V <sub>GS</sub>	±20	V
Continuous Drain Current (Silicon Limited)   T <sub>c</sub> =25°C	I <sub>D</sub>	140	A
Pulsed Drain Current	I <sub>DM</sub>	500	A
Single Pulsed Avalanche Energy (V <sub>DD</sub> =50V,L=0.5mH) <sup>(c)</sup>	E <sub>AS</sub>	506	mJ
Drain Power Dissipation	P <sub>D</sub>	300	W
Thermal Resistance from Junction to Case	R <sub>θJC</sub>	0.5	°C/W
Thermal Resistance- Junction to Ambient	R <sub>θJA</sub>	60	°C/W
Junction Temperature	T <sub>J</sub>	175	°C
Storage Temperature	T <sub>STG</sub>	-55~ +175	°C

**MOSFET ELECTRICAL CHARACTERISTICS(T<sub>a</sub>=25°C unless otherwise noted)**

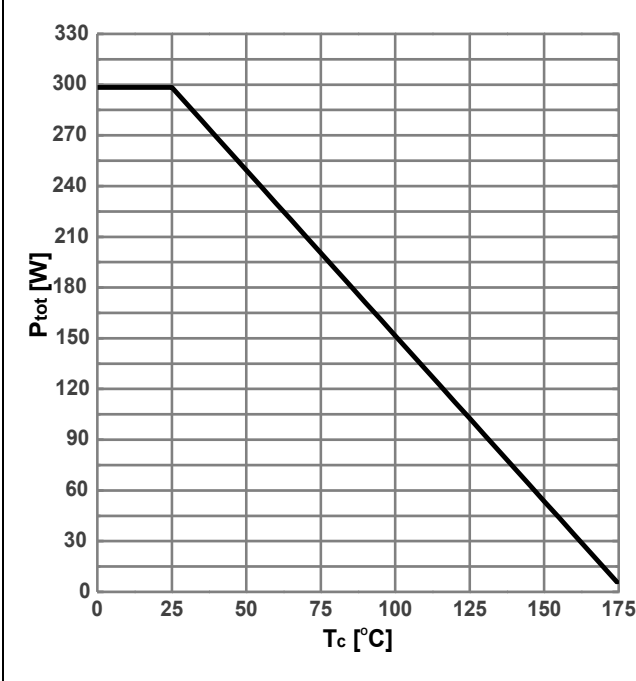
Parameter	Symbol	Test Condition	Min	Type	Max	Unit
<b>Static Characteristics</b>						
Drain-source breakdown voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> =250μA	150	-	-	V
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> =150V, V <sub>GS</sub> = 0V	-	-	1	μA
Gate-body leakage current	I <sub>GSS</sub>	V <sub>GS</sub> = ±20V, V <sub>DS</sub> = 0V	-	-	±100	nA
Gate threshold voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	2.0	2.9	4.0	V
Drain-source on-resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =20A	-	6.6	7.5	mΩ
Gate Resistance	R <sub>g</sub>	V <sub>GS</sub> =0V, V <sub>DS</sub> Open, f=1MHz		2.4		Ω
Transconductance	G <sub>fs</sub>	V <sub>DS</sub> =5V, I <sub>D</sub> =20A		80		S
<b>Dynamic characteristics</b>						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =75V, V <sub>GS</sub> =0V, f =1.0MHz	-	5240	-	pF
Output Capacitance	C <sub>oss</sub>		-	412	-	
Reverse Transfer Capacitance	C <sub>rss</sub>		-	10	-	
<b>Switching characteristics</b>						
Turn-on delay time	t <sub>d(on)</sub>	V <sub>DD</sub> =75V, I <sub>D</sub> =100A, R <sub>G</sub> =1.6Ω, V <sub>GS</sub> =10V	-	22	-	ns
Turn-on rise time	t <sub>r</sub>		-	115	-	
Turn-off delay time	t <sub>d(off)</sub>		-	44	-	
Turn-off fall time	t <sub>f</sub>		-	105	-	
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> =75V, I <sub>D</sub> =20A, V <sub>GS</sub> =10V	-	18	-	nC
Gate-Source Charge	Q <sub>gs</sub>		-	10	-	
Gate-Drain Charge	Q <sub>gd</sub>		-	72	-	
<b>Source-Drain Diode characteristics</b>						
Diode Forward voltage	V <sub>SD</sub>	T <sub>J</sub> =25°C, V <sub>GS</sub> =0V, I <sub>S</sub> =10A	-	0.76	-	V
Diode Forward current	I <sub>S</sub>	T <sub>C</sub> =25°C	-	-	140	A
Body Diode Reverse Recovery Time	t <sub>rr</sub>	T <sub>J</sub> =25°C, I <sub>F</sub> =100A, di/dt=100A/us		45		ns
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>	T <sub>J</sub> =25°C, I <sub>F</sub> =100A, di/dt=100A/us		12		uc

**Notes:**

- a) Limited by T<sub>j</sub> max. Maximum duty cycle D=0.75.
- b) Pulse width tp limited by T<sub>j</sub>,max.
- c) VDD=50V, L=0.5mH, R<sub>G</sub>=25Ω, Starting T<sub>j</sub>=25°C

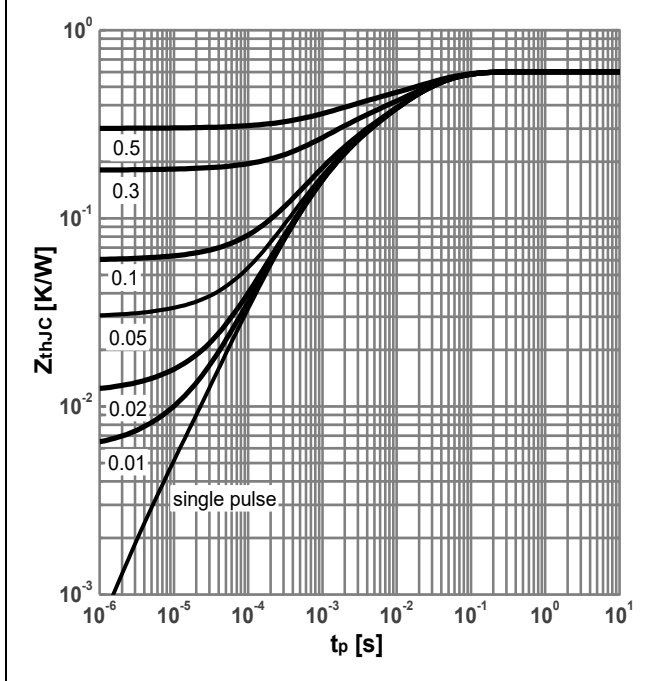
### Typical Characteristics

Diagram 1: Power dissipation



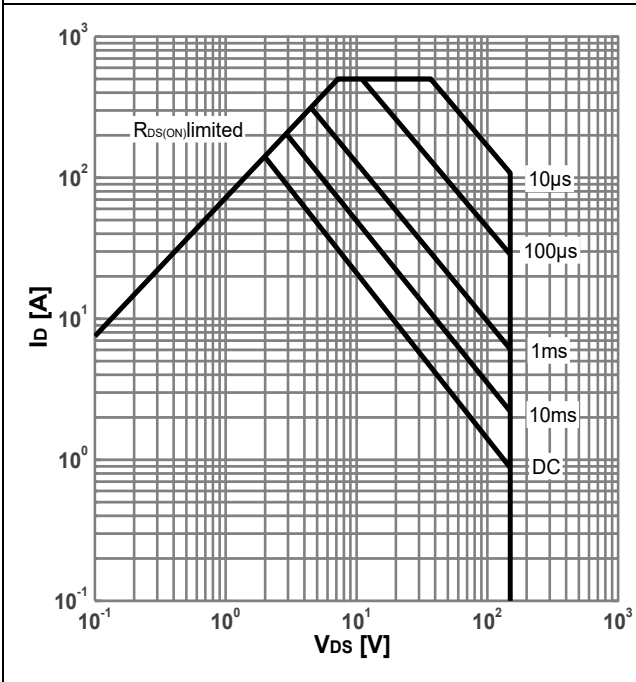
$P_{tot}=f(T_c)$

Diagram 2: Max. transient thermal impedance



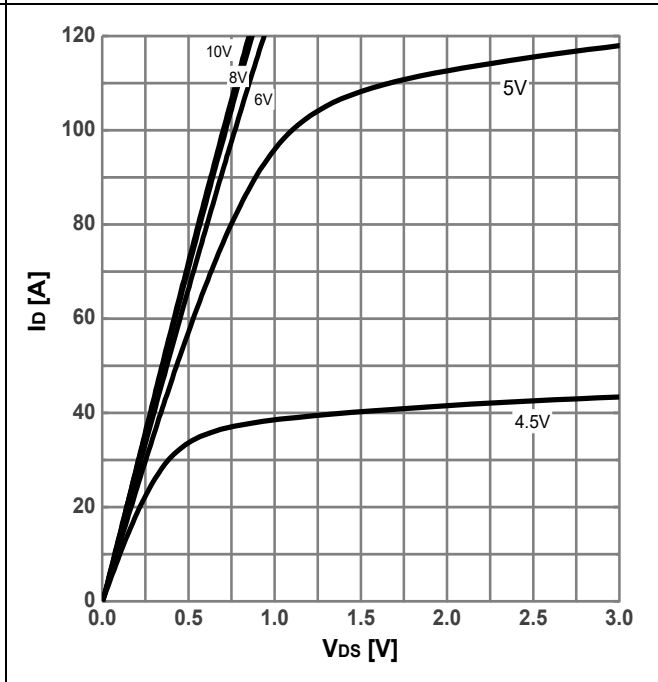
$Z_{thJC}=f(t_p)$ ; parameter:  $D= t_p/T$

Diagram 3: Safe operating area



$I_D=f(V_{DS})$ ;  $T_J=25^\circ\text{C}$ ;  $D=0$ ; parameter:  $t_p$

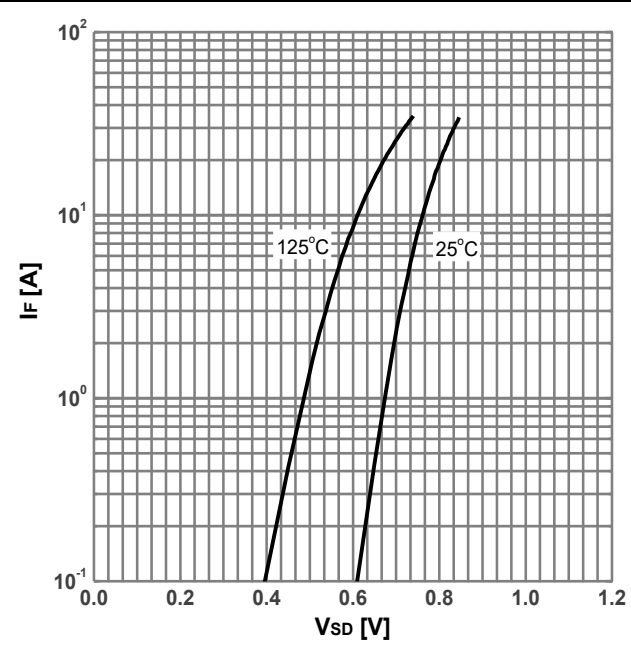
Diagram 4: Typ. output characteristics



$I_D=f(V_{DS})$ ;  $T_J=25^\circ\text{C}$ ; parameter:  $V_{GS}$

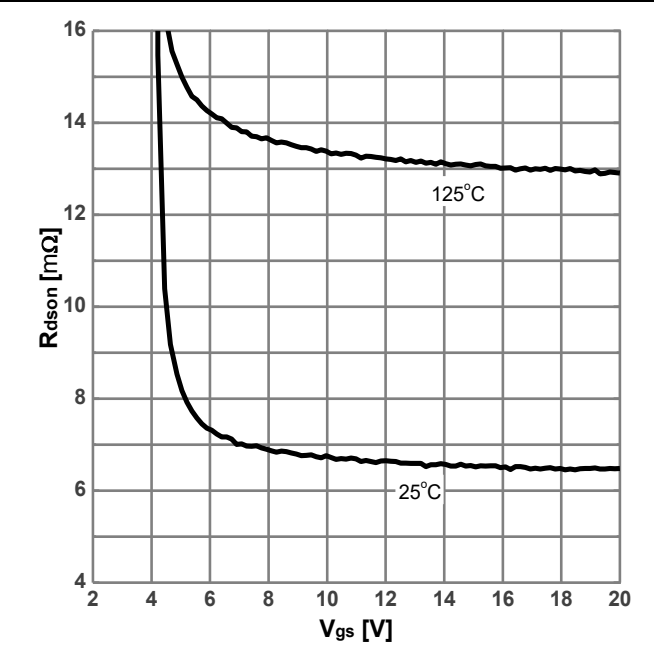
**Typical Characteristics**

**Diagram 9: Forward characteristics of reverse diode**



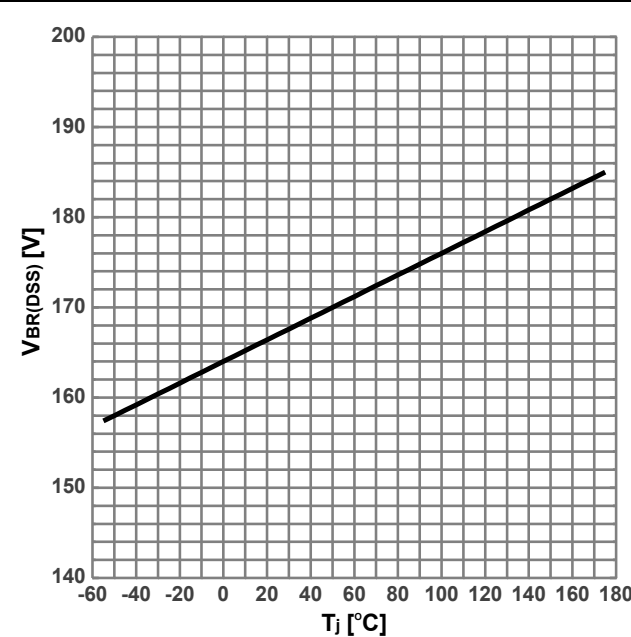
$I_F = f(V_{SD});$  parameter:  $T_j$

**Diagram 10: On state resistance vs. Vgs characteristics**



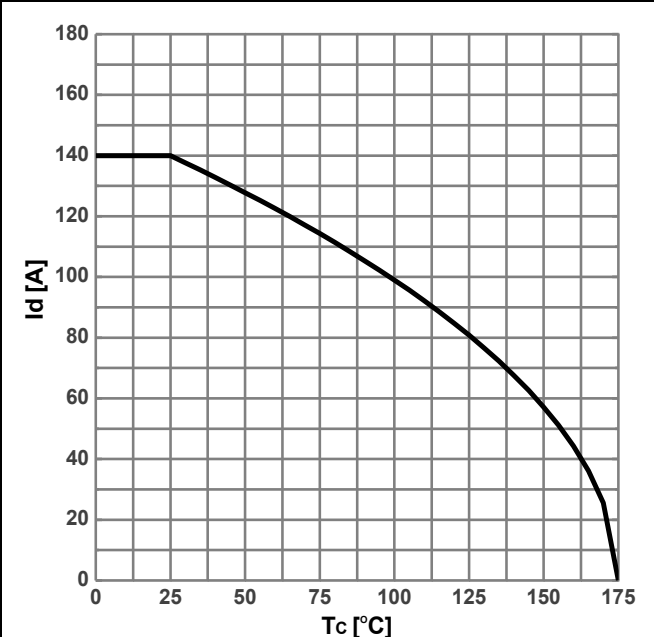
$R_{DS(on)} = f(V_{GS}); I_D = 20A;$  parameter:  $T_j$

**Diagram 11: Breakdown Voltage Variation vs. Temperature**



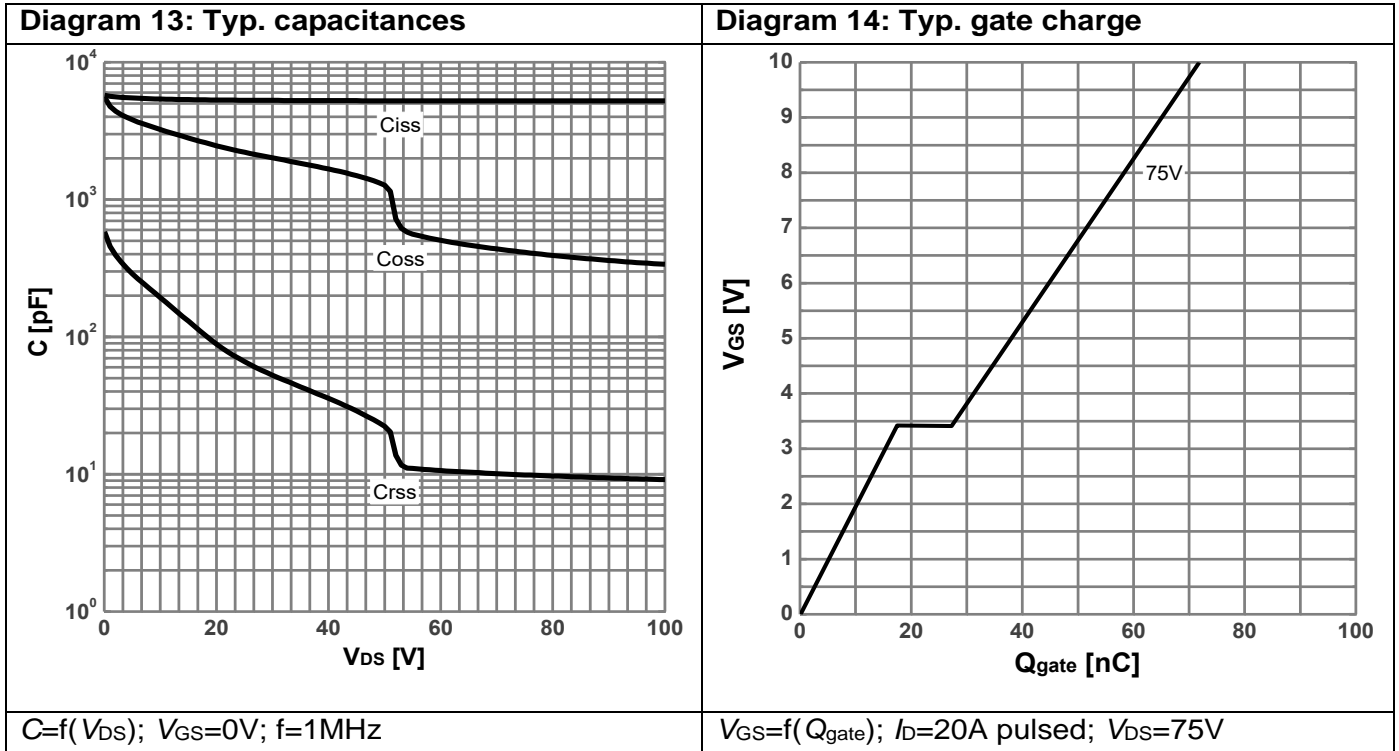
$V_{BR(DSS)} = f(T_j); I_D = 250\mu A$

**Diagram 12: Maximum Drain Current**

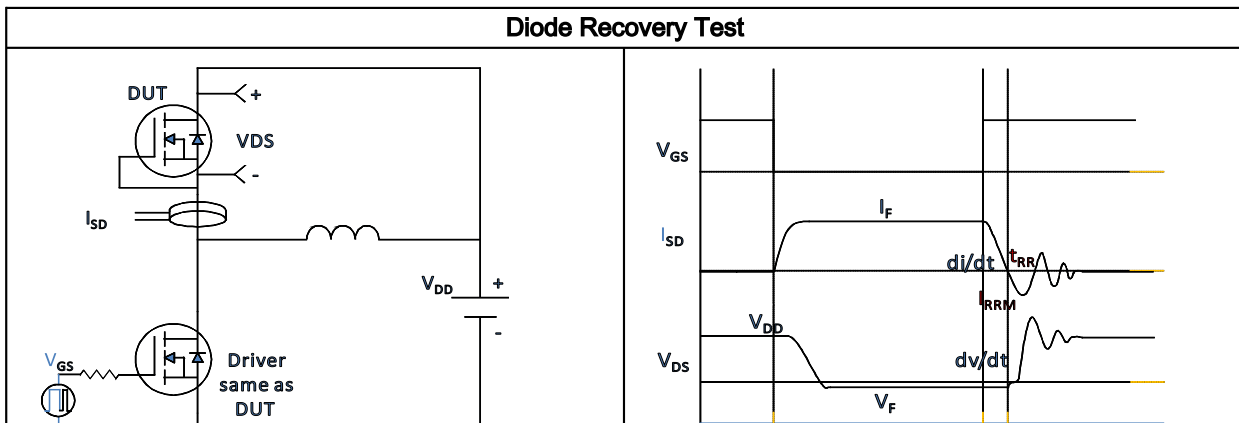
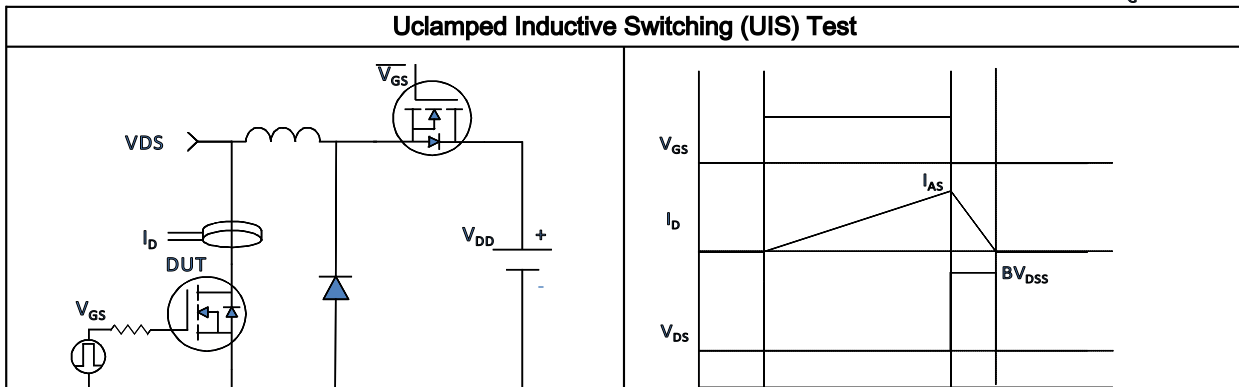
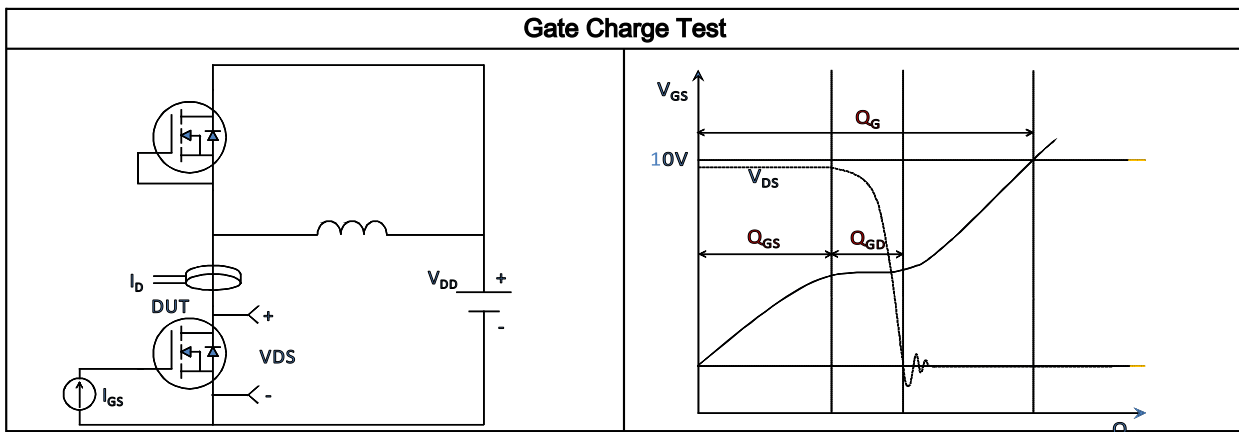
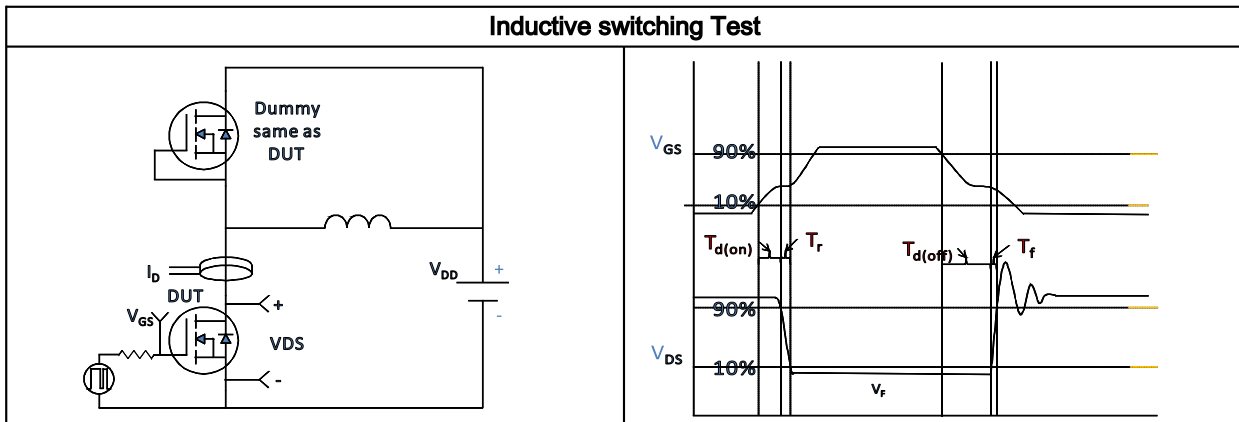


$I_D = f(T_c); V_{GS} = 10V$

**Typical Characteristics**

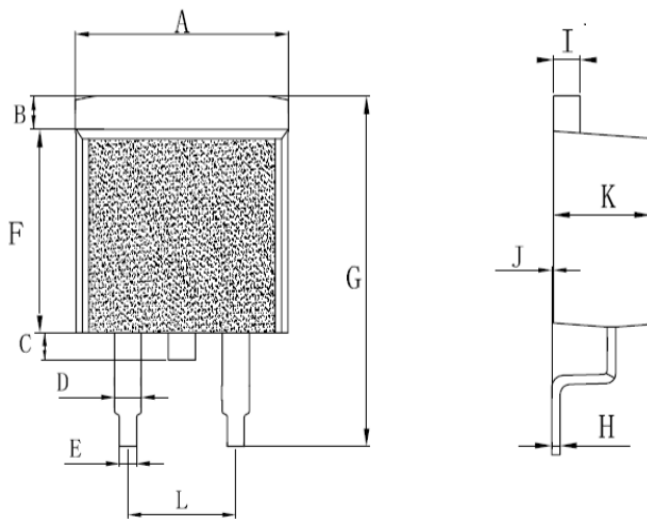


**Test Circuit**



**Package Dimensions**

T0-263



DIM.	Unit(mm)		Unit(inch)	
	Min	Max	Min	Max
A	9.7	10.4	0.381	0.409
B	1.31	1.62	0.051	0.063
C	0.65	1.22	0.025	0.048
D	1.15	1.36	0.045	0.053
E	0.62	0.95	0.024	0.037
F	8.75	9.32	0.344	0.366
G	14.75	15.8	0.580	0.622
H	0.32	0.48	0.012	0.018
I	1.18	1.36	0.046	0.053
J	0	0.15	0	0.005
K	4.38	4.86	0.172	0.191
L	4.85	5.23	0.190	0.205

## Revision History

Revision	Release	Remark
V1.0	2023/03/01	Initial Release

## Disclaimer

The information given in this document describes the independent performance of the product, but similar performance is not guaranteed under other working conditions, and cannot be guaranteed when installed with other products or equipment. To achieve the required performance of the product in actual scenarios, the customer should conduct a complete application test to assess the functionality of the product.

Allpower assumes no responsibility for equipment failures result from using products at values that exceed the ratings, operating conditions, or other parameters listed in the product specifications.

The product described in this specification is not applicable for aerospace or other applications which requires high reliability. Customers using or selling these products for use in medical, life-saving, or life-sustaining applications do so at their own risk and agree to fully indemnify.

Due to product or technical improvements, the information described or contained herein may be changed without prior notice.